L Number	Hits		DB	Time stamp
1	45283	CMP (chemical adj mechanical adj	USPAT;	2004/05/13 09:28
		polishing)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
•	54040	(N. i. m. 1.	IBM_TDB USPAT;	2004/05/12 10-07
2	54842	(high adj pressure) with (low adj		2004/05/13 10:07
		pressure)	US-PGPUB; EPO; JPO;	i
			DERWENT;	
			IBM TDB	
3	1682	first adj polishing	USPAT:	2004/05/13 09:28
3	1002	l lilia and bollowing	US-PGPUB;	2001,00,10 03.20
			EPO; JPO;	
	1		DERWENT;	
			IBM TDB	
4	1608	second adj polishing	USPĀT;	2004/05/13 09:29
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		·	IBM_TDB	
5	0	((high adj pressure) with (low adj	USPAT;	2004/05/13 09:29
	į –	pressure)) same (first adj polishing) same	US-PGPUB;	
		(second adj polishing)	EPO; JPO;	}
			DERWENT;	
_			IBM_TDB	
6	1004	(first adj polishing) same (second adj	USPAT;	2004/05/13 09:29
		polishing)	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
7	3	(CMP (chemical adj mechanical adj	USPAT;	2004/05/13 09:30
,		polishing)) and ((high adj pressure) with	US-PGPUB;	2004/03/13 09.30
		(low adj pressure)) and ((first adj	EPO; JPO;	
		polishing) same (second adj polishing))	DERWENT;	
			IBM TDB	
8	58	chadda.in.	USPĀT;	2004/05/13 09:33
	Į.		US-PGPUB;	
	1		EPO; JPO;	
			DERWENT;	
			IBM_TDB	
10	17576	pretreat pretreating	USPAT;	2004/05/13 09:33
			US-PGPUB;	
			EPO; JPO;	
	ľ		DERWENT;	
11	2706	matalliand add austras	IBM_TDB	2004/05/12 00.24
11	2706	metallized adj surface	USPAT; US-PGPUB;	2004/05/13 09:34
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
12	57987	(metallized metal) adj surface	USPAT;	2004/05/13 09:34
		, , 	US-PGPUB;	,
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
13	187	(pretreat pretreating) same ((metallized	USPĀT;	2004/05/13 09:34
		metal) adj surface)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
1.4	1	return cat catalant	IBM_TDB	0004/05/13 55 5:
14	1004	(first adj polishing) same (second adj	USPAT;	2004/05/13 09:34
		polishing)	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
				0004/05/12 00 25
15	n	((pretreat pretreating) same ((metallized	IUSPAT:	2004/05/13 09:35
15	0	((pretreat pretreating) same ((metallized metal) adj surface)) and ((first adj	USPAT; US-PGPUB;	2004/05/13 09:35
15	0	metal) adj surface)) and ((first adj	US-PGPUB;	2004/05/13 09:35
15	0			2004/05/13 09:35

16	60188	(remove removing removed) adj3 film	USPAT;	2004/05/13 09:36
1		(10.10.10.10.10.10.10.10.10.10.10.10.10.1	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
17	39	(pretreat pretreating) same ((remove	USPAT;	2004/05/13 09:36
		removing removed) adj3 film)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
1,0	,	(1000-100-100-100-100-100-100-100-100-10	IBM_TDB	2004/05/12 00:26
18	1	((pretreat pretreating) same ((remove removing removed) adj3 film)) and (CMP	USPAT; US-PGPUB;	2004/05/13 09:36
1		(chemical adj mechanical adj polishing))	EPO; JPO;	
		i (chemical adj mechanical adj polishing),	DERWENT;	
			IBM TDB	
19	l 8	(pretreat pretreating) and ((first adj	USPAT;	2004/05/13 09:36
	_	polishing) same (second adj polishing))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
20	17	(CMP (chemical adj mechanical adj	USPĀT;	2004/05/13 09:57
1	1	polishing)) same ((high adj pressure) with	US-PGPUB;	
1	1	(low adj pressure))	EPO; JPO;	
]		DERWENT;	
21	006		IBM_TDB USPAT;	2004/05/13 09:58
21	826	yoshida.in. near hideaki.in.	USPAT; US-PGPUB;	2004/05/13 09:58
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
22	7	(yoshida.in. near hideaki.in.) and	USPAT;	2004/05/13 09:58
		planarizing	US-PGPUB;	
1		•	EPO; JPO;	
			DERWENT;	
•			IBM_TDB	
25	148	(pretreat pretreating) with ((metallized	USPAT;	2004/05/13 10:05
		metal) adj surface)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
126	1	(/	IBM_TDB	2004/05/12 10:05
26	1	((pretreat pretreating) with ((metallized metal) adj surface)) and (CMP (chemical	USPAT; US-PGPUB;	2004/05/13 10:05
		adj mechanical adj polishing))	EPO; JPO;	
		adj mechanical adj polishing,,	DERWENT;	
			IBM TDB	
27	8	((pretreat pretreating) with ((metallized	USPĀT;	2004/05/13 10:07
1		metal) adj surface)) and ((remove removing	US-PGPUB;	
		removed) adj3 film)	EPO; JPO;	
			DERWENT;	İ
			IBM_TDB	
28	4	' '	USPAT;	2004/05/13 10:07
1		pressure)) and ((first adj polishing) same	US-PGPUB;	
		(second adj polishing))	EPO; JPO;	
			DERWENT; IBM TDB	
29	15321	 (first adj pressure) with (second adj	USPAT;	2004/05/13 10:08
	15521	pressure)	US-PGPUB;	
		F	EPO; JPO;	
,			DERWENT;	
1			IBM TDB	
30	174		USPAT;	2004/05/13 10:08
		polishing)) and ((first adj pressure) with	US-PGPUB;	
		(second adj pressure))	EPO; JPO;	
			DERWENT;	
,			IBM_TDB	
31	38	'''	USPAT;	2004/05/13 10:08
		pressure)) and ((CMP (chemical adj	US-PGPUB;	
		<pre>mechanical adj polishing)) and ((first adj pressure) with (second adj pressure)))</pre>	EPO; JPO; DERWENT;	
		pressure, wrom (second ad) pressure;;;	IBM TDB	
L	L		+011 100	

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32	7	((first adj polishing) same (second adj	USPAT;	2004/05/13 10:08
	•	polishing)) and ((CMP (chemical adj	US-PGPUB;	
		mechanical adj polishing)) and ((first adj	EPO; JPO;	
		pressure) with (second adj pressure)))	DERWENT;	
			IBM TDB	

